

COPPER/COPPER ALLOY SURFACE BONDING PROMOTOR AND ITS USAGE

ABSTRACT OF THE DISCLOSURE

5 A halogen ion/hydrogen peroxide-free copper/copper alloy
surface bonding promotor includes copper oxidant 0.1~20wt%,
acidic solution prepared from organic acid, inorganic acid, or their
compound 5~20wt%, and nonionic compound 0.001~10wt%. The
use of the halogen ion/hydrogen peroxide-free copper/copper alloy
10 surface bonding promotor enables the copper/copper alloy to have a
rough surface that exhibits excellent adhesion to resins and
superior solderability.